

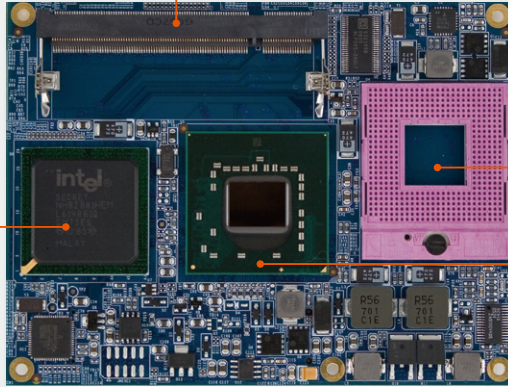


ESM-GME965

Intel® Core™ 2 Duo COM Express Module with Intel® GME965 + ICH8-M Chipset



One 200-pin SODIMM Up to 2GB DDR2 SDRAM



Intel® ICH8-M Chipset

Supports 65nm Intel® Core™ Duo/ Core™ 2 Duo CPU

Intel® GME965 Chipset

Features

- Supports 65nm Intel® µFC-PGA 478 / µFC-BGA 479 Core™ 2 Duo CPU
- Intel® GME965/ ICH8-M Chipset
- One 200-pin SODIMM Up to 2GB DDR2 400/ 533/ 667 SDRAM
- Dual View, Dual-channel LVDS
- Intel® High Definition Audio
- Broadcom BCM5786 Gigabit Ethernet
- 4 PCI, 5 PCIe1, 1 PCIe16, 3 SATA, 8 USB, 8-bit GPIO

Intel® GME965	Dual View	GbE	4 PCI	5 PCIe1
1 PCIe16	3 SATA	8 USB	8 GPIO	

Specifications

System

CPU	Supports 65nm Intel® µFC-PGA 478/ µFC-BGA 479 (Socket P) Core™ 2 Duo CPU Note: Available in Different CPU Speeds by Request
BIOS	Award 8Mbit Flash BIOS
System Chipset	Intel® GME965/ ICH8-M
System Memory	One 200-pin SODIMM Socket Supports Up to 2 GB DDR2 400/ 533/ 667 SDRAM
Expansion	4 x PCI (PCI Rev. 2.3 Compliant), 5 x PCIe1, 1 x PCIe16

I/O

MIO	1 x EIDE (Ultra DMA 100), LPC, SMBus / I ² C Bus, 3 x SATA
USB	8 x USB 2.0
DIO	4-bit GPI and 4-bit GPO

Display

Chipset	Intel® GME965 Integrated
Display Memory	Intel® DVM T 4.0 Supports Up to 384MB Shared Video Memory
Resolution	CRT Mode: 2048 x 1536 @ 32bpp (60Hz) LCD/ Simultaneous Mode: 1600 x 1200 @ 16bpp (75Hz) Widescreen Mode: 1920 x 1200 @ 32bpp (65Hz)
Multiple Display	CRT + LVDS
LVDS Interface	Dual-channel 18/ 24-bit LVDS

Audio Interface

Chipset	Intel® ICH8-M
Interface	Intel® High Definition Audio

Ethernet

LAN	Broadcom BCM5786 Gigabit Ethernet, Supports Wake on LAN
Ethernet Interface	1000 Base-Tx Gigabit Ethernet Compatible

Mechanical & Environmental

Power Requirement	+12V @ 4.42A, +5Vsb @ 0.22A (with Intel® Core™ 2 Duo T7500 2.2GHz & 1GB DDR2 667 SDRAM)
Power Type	ATX
Operating Temperature	0 ~ 60°C (32 ~ 140°F)
Storage Temperature	-40 ~ 75°C (-40 ~ 167°F)
Operating Humidity	0% ~ 90% Relative Humidity, Non-condensing
Size (L x W)	5" x 3.7" (125mm x 95mm)
Weight	0.44lbs (0.2kg)

Ordering Information

- ESM-GME965**
Intel® Core™ 2 Duo COM Express Module with Intel® GME965 + ICH8-M Chipset
- EEV-EX13**
COM Express Carrier Board for Evaluation
- ACC-HSP-2852-1R**
Heat Spreader for ESM-945GME/ GME965 Series with PGA Type, 125 x 95 x 11mm
- ACC-HSP-2852-2R**
Heat Spreader for ESM-945GME/ GME965 Series with BGA Type, 125 x 95 x 11mm
- ACC-HSK-2852-1R**
Heatsink with Fan for ESM-945GME/ GME965 Series with PGA Type, 125 x 95 x 36mm

- 1 Embedded System
- 2 ETX/XTX/COM Express
- 3 3.5" SBC
- 4 EPIC
- 5 5.25" SBC
- 6 PC/104
- 7 ATX
- 8 Micro ATX
- 9 Mini ITX
- 10 Nano ITX
- 11 ACP
- 12 Mini ITX System
- 13 Peripherals
- 14 Index